

Stack-up and Viaspans

Board Type Rigid
Layers 4

Board structure Standard
Laminations 1

Materials None

RIGID PART

Total Thickness

1.610 mm

#	Definition	Type	Thickness
	Soldermask	SM = 0,015 mm	0.015
1	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,120 mm	0.12
2	Copper	CU 35 um	0.035
	CORE	IL 1,20	1.2
3	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,120 mm	0.12
4	Copper	CU 35 um	0.035
	Soldermask	SM = 0,015 mm	0.015